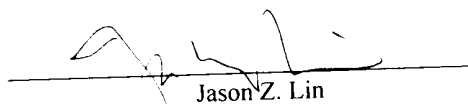


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: **09/627,979** Examiner: **DiLinh Nguyen**  
Inventor: **Randy H. Y. Lo, Chi-Chuan Wu and Ssu-Cheng Lai**  
Filed: **June 24, 2000** Art Unit: **2814**  
Title: **Method Of Packaging Multi Chip Module**

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Box Non-Fee Amendment, Commissioner for Patents, Washington, D.C. 20231, on the date shown below.

  
Jason Z. Lin

Oct. 3, 2001  
Date

Honorable Commissioner for Patents  
Washington, D.C. 20231

RESPONSE TO ELECTION/RESTRICTION REQUIREMENT

Sir:

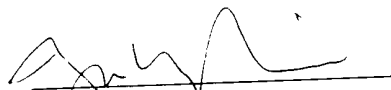
AMENDMENTCLAIMS:

Please cancel claims **27-40**.

REMARKS

In response to the election/restriction requirement in the Office Action dated **09/05/2001**, applicants elect **claims 1-26 drawn to a semiconductor device** of the invention to prosecute without traverse.

Respectfully submitted,

  
Jason Z. Lin  
Agent for Applicants  
Reg. No. 37,492  
19597 Via Monte Drive  
Saratoga, CA 95070  
(408) 867-9757